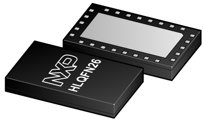

SOT1831-1

HLQFN26, thermal enhanced low profile quad flat package, no leads, 1 mm pitch, 10 mm x 6 mm x 1.348 mm body

9 December 2019 Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFN26
Package style descriptive code	HLQFN (thermal enhanced low profile quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-09-2019
Manufacturer package code	98ASA00953D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	5.9	6	6.1	mm
package height	1.278	1.348	1.418	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	26	-	

2 Package outline

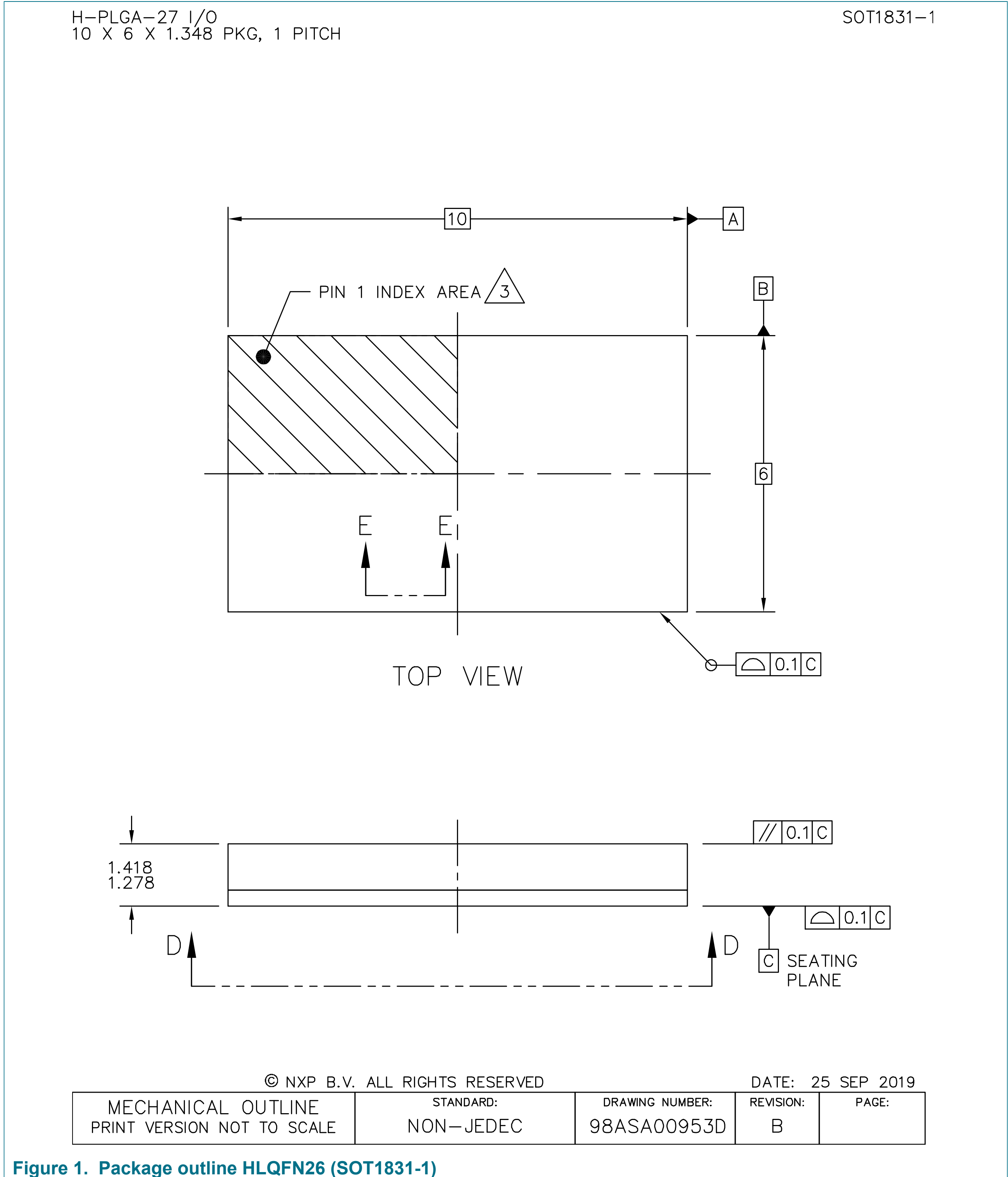

Figure 1. Package outline HLQFN26 (SOT1831-1)

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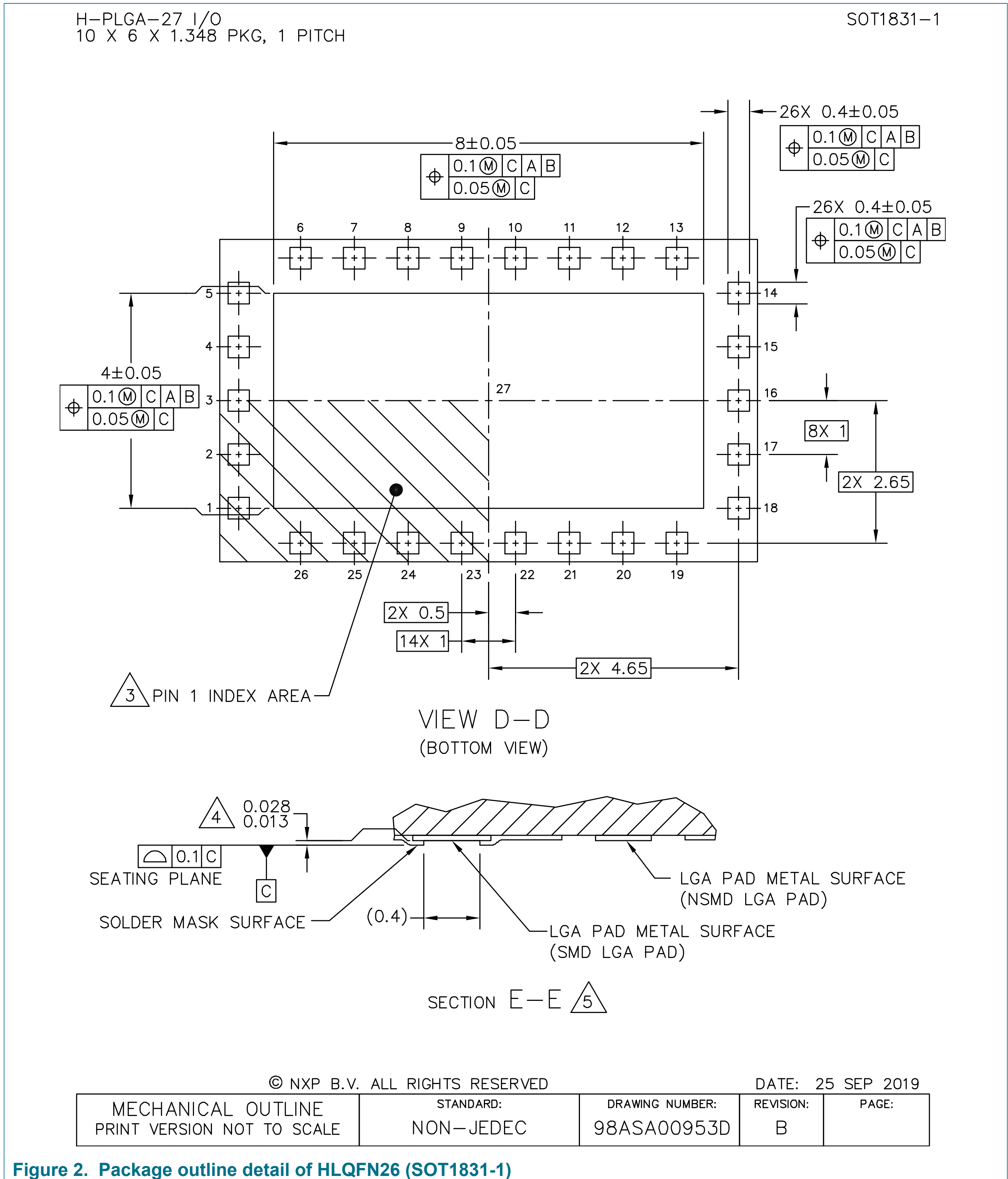

Figure 2. Package outline detail of HLQFN26 (SOT1831-1)

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3 Soldering

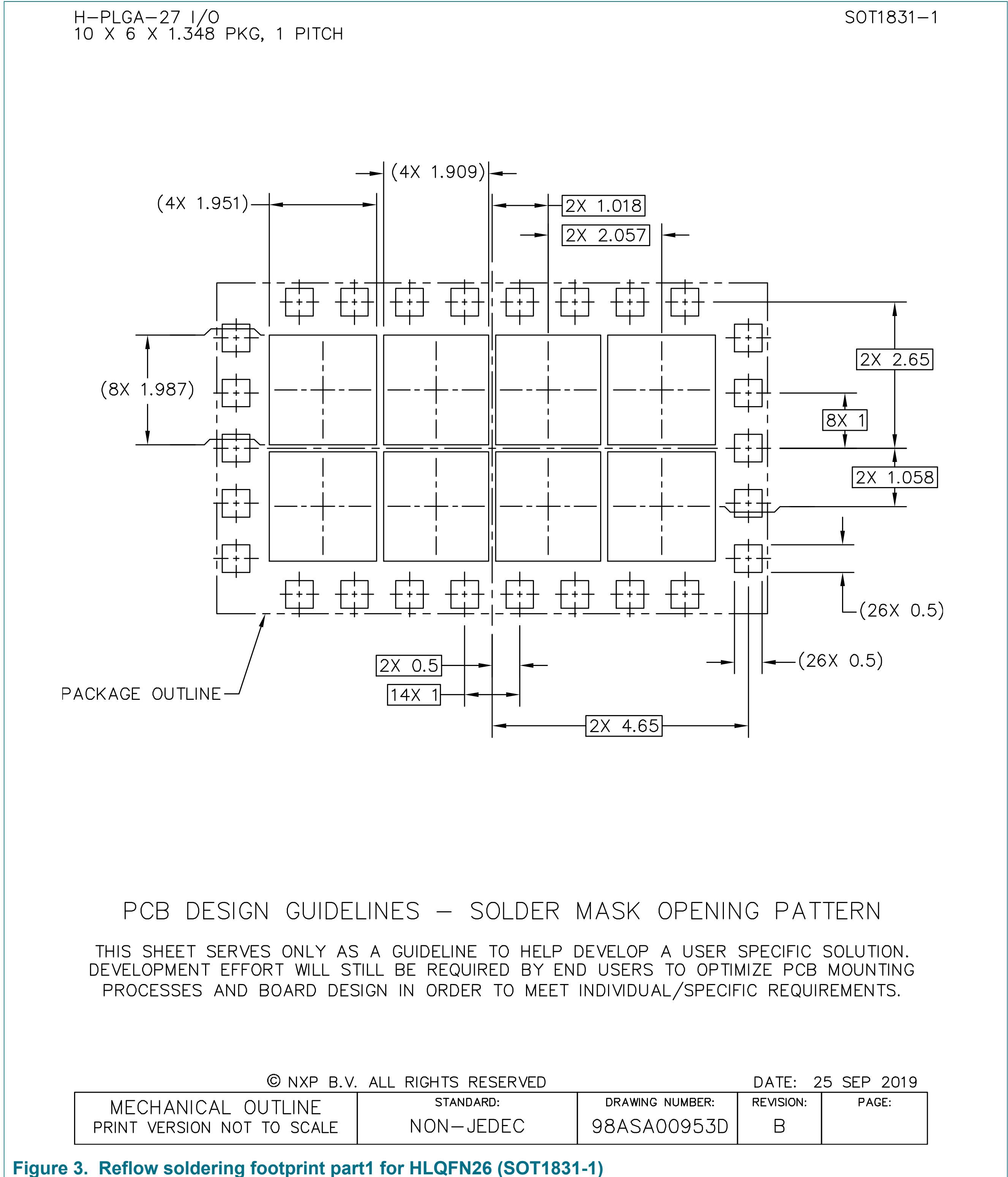

Figure 3. Reflow soldering footprint part1 for HLQFN26 (SOT1831-1)

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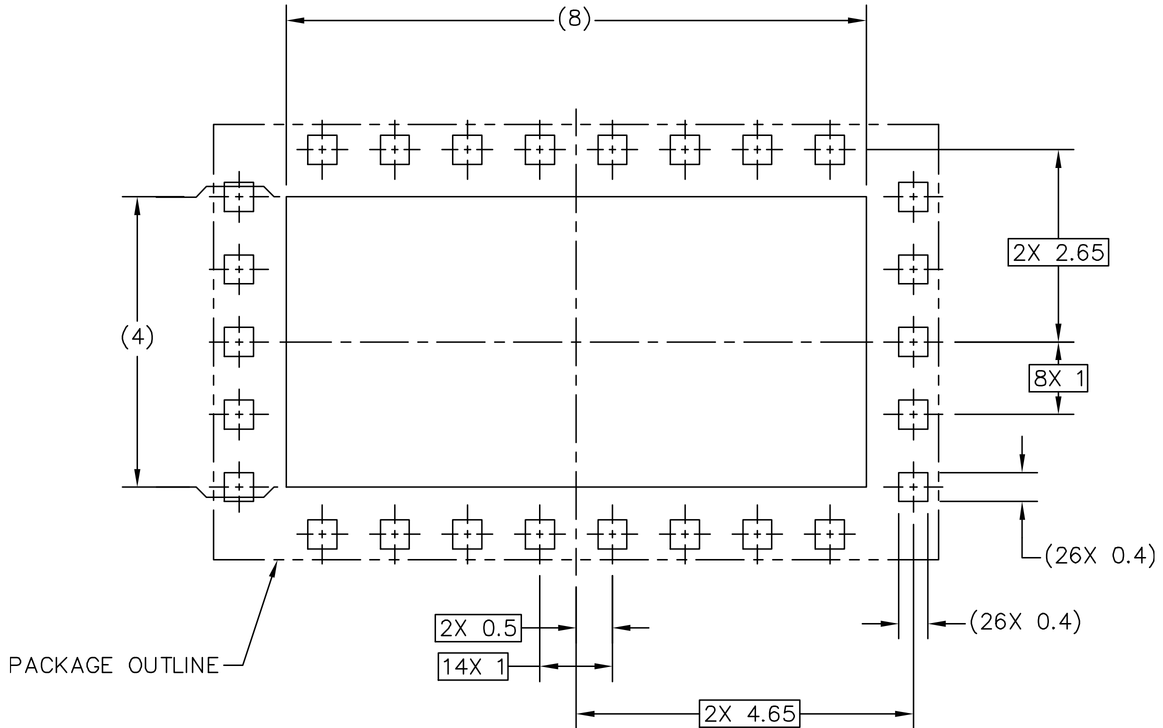
H-PLGA-27 I/O
10 X 6 X 1.348 PKG, 1 PITCH

SOT1831-1



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DATE: 25 SEP 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA00953D	REVISION: B	PAGE:

Figure 4. Reflow soldering footprint part2 for HLQFN26 (SOT1831-1)

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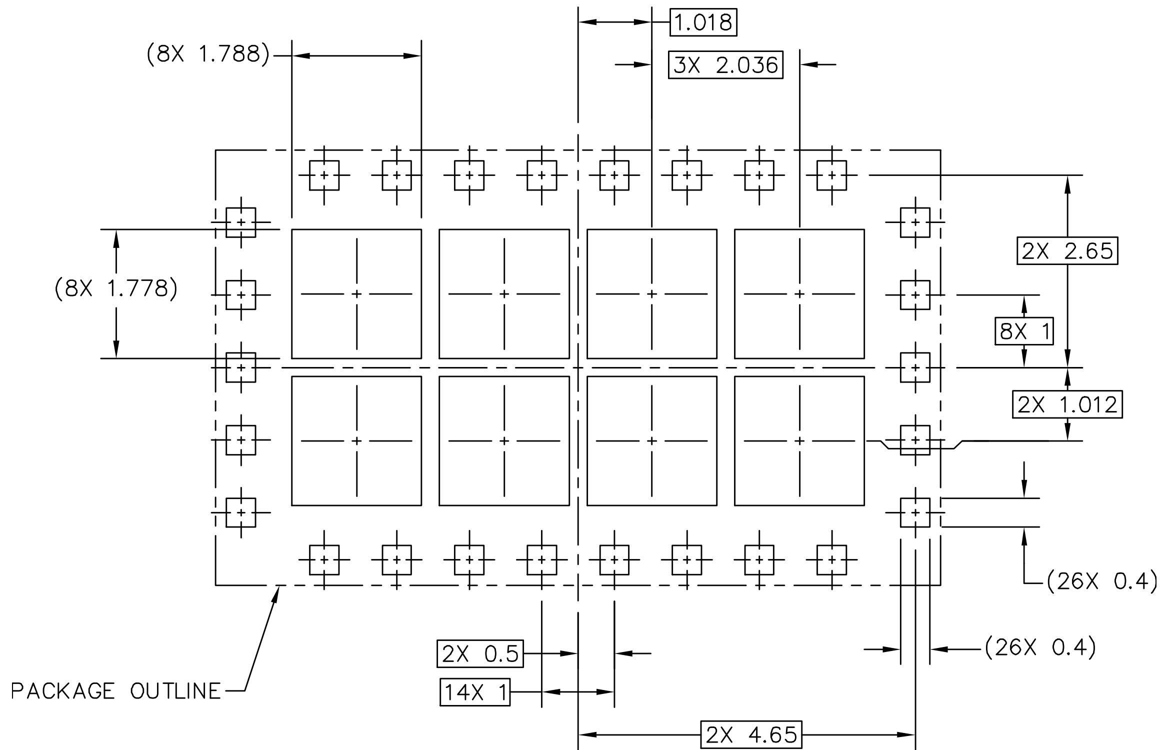
H-PLGA-27 I/O
10 X 6 X 1.348 PKG, 1 PITCH

SOT1831-1



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HLQFN26 (SOT1831-1)

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H-PLGA-27 I/O
10 X 6 X 1.348 PKG, 1 PITCH

SOT1831-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DIMENSION APPLIES TO ALL LEADS AND FLAG.

5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 27) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON-SOLDERMASK DEFINED (NSMD).

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Figure 6. Package outline note HLQFN26 (SOT1831-1)

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